**GP1S93** 

### **■** Features

1. Low height type (Height: 3.1 mm)

2. Wide gap type (Gap: 2.0 mm)

3. Detector side slit width: (0.3) mm

## **■** Applications

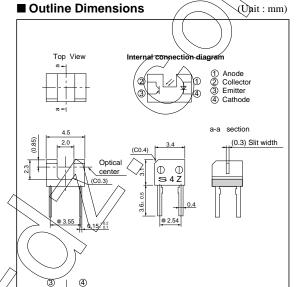
1. FDDs

2. Cameras

3. Camera-integral VCRs

# = 0 · 41'- · · D'- · · · · · · · ·

Subminiature Photointerrupter

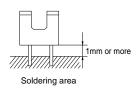


\* Tolerance : ± 0.2
\* (): Reference dimensions
\* The dimensions indicated by \* refer to those measured from the lead base.

■ Absolute Maximum Ratings

(Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	$I_F$	50	mA
	Reverse voltage	$V_R$	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	$V_{CEO}$	35	V
	Emitter-collector voltage	V <sub>ECO</sub>	6	V
	Collector current	$I_C$	20	mA
	Collector power dissipation	$P_{C}$	75	mW
	Total power dissipation	P <sub>tot</sub>	100	mW
	Operating temperature	$T_{opr}$	- 25 to + 85	°C
Storage temperature		$T_{stg}$	- 40 to + 100	°C
	*Soldering temperature	$T_{sol}$	260	°C



<sup>\*1</sup> For 5 seconds

# **■** Electro-optical Characteristics

Parameter			Symbol	Conditions	MIN.	TYP.	MAX. Unit
Immust	Forward voltage		VF	$I_F = 20mA$	-	1.2	1.4 V
Input	Reverse current		$I_R$	$V_R = 3V$	-	-	10 µA
Output	Dark current		I <sub>CEO</sub>	$V_{\text{CE}} = 20V$	-		$1 \times 10^7$ A
	Collector current		Ic	$I_F = 5mA$ , $V_{CE} = 5V$	100	(-(	400\ µA
Transfer	Collector-emitter satura	ation voltage	V CE(sat)	$I_F = 10 \text{mA}, I_C = 40 \mu \text{ A}$	-	[-	0,4 / V
characteristics	Response time	Rise time	t <sub>r</sub>	$I_C = 0.1$ mA, $V_{CE} = 5$ V, $R_L = 1$ k $\Omega$		50	150 µs
		Fall time	$t_{\mathrm{f}}$		1	-/ 50\ <u></u>	150 μs

Fig. 1 Forward Current vs. Ambient **Temperature** 

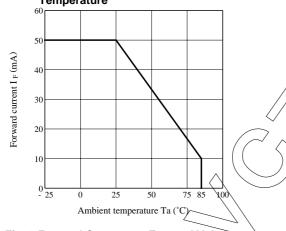


Fig. 3 Forward Current vs. Forward Voltage

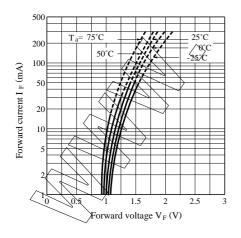


Fig. 2 Power Dissipation vs.

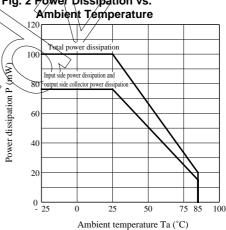


Fig. 4 Collector Current vs. Forward Current

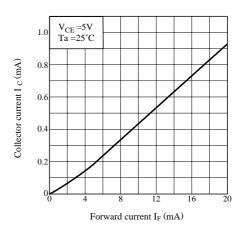


Fig. 5 Collector Current vs. Collector-emitter Voltage

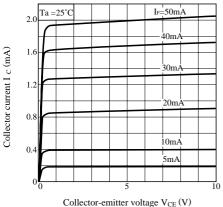


Fig. 7 Collector-emitter Saturation Voltage vs. Ambient Temperature

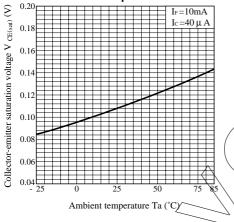


Fig. 9 Response Time vs. Load Resistance

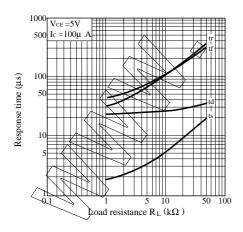


Fig. 6 Relative Collector Current vs.

Ambient Temperature

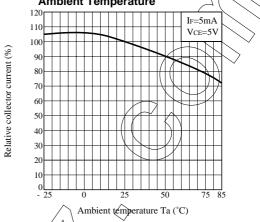
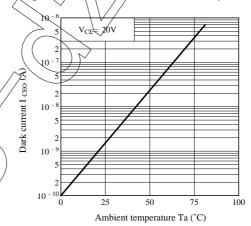
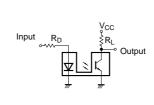


Fig. 8 Dark Current vs. Ambient Temperature



**Test Circuit for Response Time** 



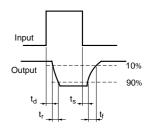
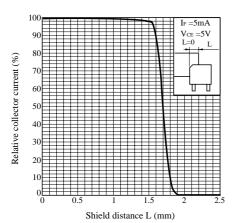
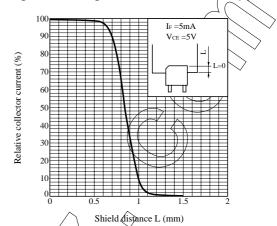


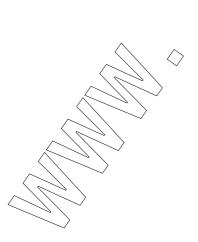
Fig. 10 Detecting Position Characteristics (1)



• Please refer to the chapter "Precautions for Use".

Fig. 11 Detecting Position Characteristics (2)





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- Audio visual equipment
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